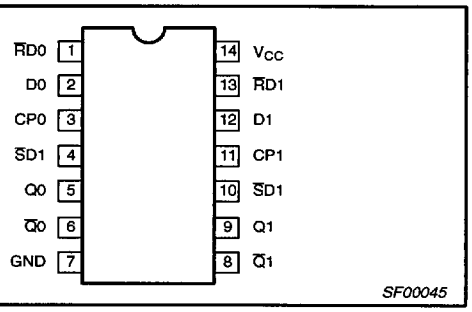
Dual D-type flip-flop

74ABT74

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T_{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t_{PLH} t_{PHL}	Propagation delay CPn to Qn, $\overline{Q}$n	C_L = 50pF; V_{CC} = 5V	3.0 2.5	ns
t_{OSLH} t_{OSHL}	Output to Output skew		0.5	ns
C_{IN}	Input capacitance	V_I = 0V or V_{CC}	3	pF
I_{CC}	Total supply current	Outputs disabled; V_{CC} = 5.5V	50	µA

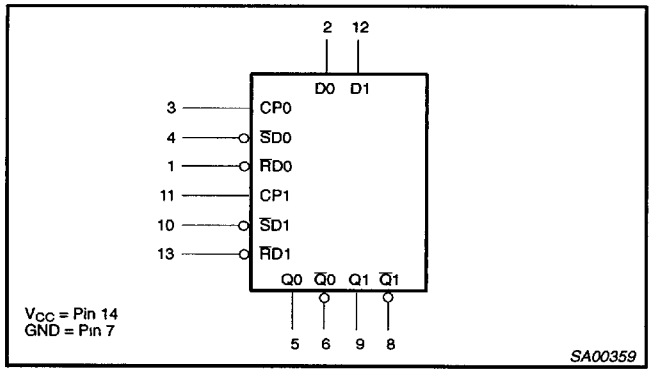
PIN CONFIGURATION



PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 2, 3, 4, 10, 11, 12, 13	$\overline{R}$Dn, Dn, CPn, $\overline{S}$Dn	Data inputs
5, 6, 8, 9	Qn, $\overline{Q}$n	Data outputs
7	GND	Ground (0V)
14	V_{CC}	Positive supply voltage

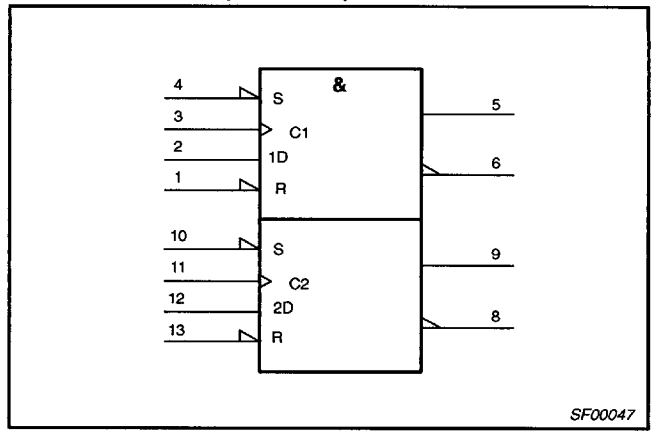
LOGIC SYMBOL



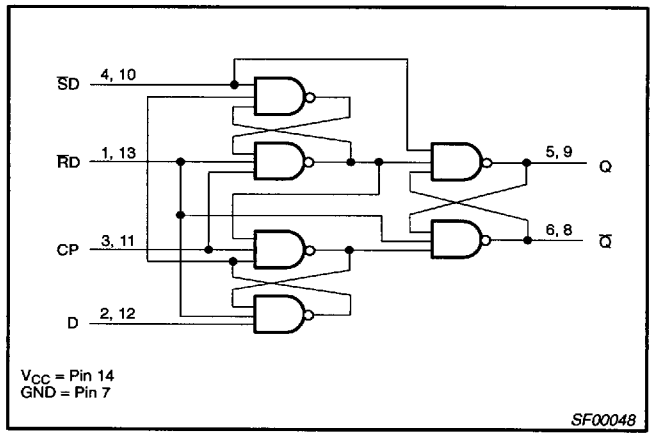
DESCRIPTION

The 74ABT74 is a dual positive edge-triggered D-type flip-flop featuring individual data, clock, set, and reset inputs; also true and complementary outputs. Set ($\overline{S}$D) and reset ($\overline{R}$D) are asynchronous active low inputs and operate independently of the clock input. When set and reset are inactive (high), data at the D input is transferred to the Q and $\overline{Q}$ outputs on the low-to-high transition of the clock. Data must be stable just one setup time prior to the low-to-high transition of the clock for predictable operation. Clock triggering occurs at a voltage level and is not directly related to the transition time of the positive-going pulse. Following the hold time interval, data at the D input may be changed without affecting the levels of the output.

LOGIC SYMBOL (IEEE/IEC)



LOGIC DIAGRAM



ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
14-Pin Plastic DIP	–40°C to +85°C	74ABT74 N	74ABT74 N	SOT27-1
14-Pin plastic SO	–40°C to +85°C	74ABT74 D	74ABT74 D	SOT108-1
14-Pin Plastic SSOP Type II	–40°C to +85°C	74ABT74 DB	74ABT74 DB	SOT337-1
14-Pin Plastic TSSOP Type I	–40°C to +85°C	74ABT74 PW	74ABT74PW DH	SOT402-1

FUNCTION TABLE

INPUTS				OUTPUTS		OPERATING MODE
$\overline{SD}$	$\overline{RD}$	CP	D	Q	$\overline{Q}$	
L	H	X	X	H	L	Asynchronous set
H	L	X	X	L	H	Asynchronous reset
L	L	X	X	H	H	Undetermined*
H	H	↑	h	H	L	Load "1"
H	H	↑	l	L	H	Load "0"
H	H	↕	X	NC	NC	Hold

NOTES:
H = High voltage level
h = High voltage level one setup time prior to low-to-high clock transition
L = Low voltage level
l = Low voltage level one setup time prior to low-to-high clock transition
NC= No change from the previous setup
X = Don't care
↑ = Low-to-high clock transition
↕ = Not low-to-high clock transition
* = This setup is unstable and will change when either set or reset return to the high level.

ABSOLUTE MAXIMUM RATINGS[1, 2]

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		−0.5 to +7.0	V
I_{IK}	DC input diode current	$V_I < 0$	−18	mA
V_I	DC input voltage[3]		−1.2 to +7.0	V
I_{OK}	DC output diode current	$V_O < 0$	−50	mA
V_{OUT}	DC output voltage[3]	output in Off or High state	−0.5 to +5.5	V
I_{OUT}	DC output current	output in Low state	40	mA
T_{stg}	Storage temperature range		−65 to 150	°C

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		MIN	MAX	
V_{CC}	DC supply voltage	4.5	5.5	V
V_I	Input voltage	0	V_{CC}	V
V_{IH}	High-level input voltage	2.0		V
V_{IL}	Low-level input voltage		0.8	V
I_{OH}	High-level output current		−15	mA
I_{OL}	Low-level output current		20	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
T_{amb}	Operating free-air temperature range	−40	+85	°C

DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			T_{amb} = +25°C			T_{amb} = –40°C to +85°C		
			MIN	TYP	MAX	MIN	MAX	
V_{IK}	Input clamp voltage	V_{CC} = 4.5V; I_{IK} = –18mA		–0.9	–1.2		–1.2	V
V_{OH}	High-level output voltage	V_{CC} = 4.5V; I_{OH} = –15mA; V_I = V_{IL} or V_{IH}	2.5	2.9		2.5		V
V_{OL}	Low-level output voltage	V_{CC} = 4.5V; I_{OL} = 20mA; V_I = V_{IL} or V_{IH}		0.35	0.5		0.5	V
I_I	Input leakage current	V_{CC} = 5.5V; V_I = GND or 5.5V		±0.01	±1.0		±1.0	µA
I_{OFF}	Power-off leakage current	V_{CC} = 0.0V; V_O or V_I ≤ 4.5V		±5.0	±100		±100	µA
I_{CEX}	Output High leakage current	V_{CC} = 5.5V; V_O = 5.5V; V_I = GND or V_{CC}		5.0	50		50	µA
I_O	Output current[1]	V_{CC} = 5.5V; V_O = 2.5V	–50	–75	–180	–50	–180	mA
I_{CC}	Quiescent supply current	V_{CC} = 5.5V; V_I = GND or V_{CC}		2	50		50	µA
ΔI_{CC}	Additional supply current per input pin[2]	V_{CC} = 5.5V; One data input at 3.4V, other inputs at V_{CC} or GND		0.25	500		500	µA

NOTES:
1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
2. This is the increase in supply current for each input at 3.4V.
3. For valid test results, data must not be loaded into the flip-flop or latch after applying the power.

AC ELECTRICAL CHARACTERISTICS

GND = 0V; t_R = t_F = 2.5ns; C_L = 50pF, R_L = 500Ω

SYMBOL	PARAMETER	WAVEFORM	LIMITS					UNIT
			T_{amb} = +25°C V_{CC} = +5.0V			T_{amb} = –40°C to +85°C V_{CC} = +5.0V ±0.5V		
			MIN	TYP	MAX	MIN	MAX	
f_{MAX}	Maximum clock frequency	1	180	250		150		MHz
t_{PLH} t_{PHL}	Propagation delay CPn to Qn, $\overline{Q}$n	1	1.0 1.0	3.0 2.5	4.2 3.5	1.0 1.0	4.7 4.0	ns
t_{PLH} t_{PHL}	Propagation delay $\overline{S}$n, $\overline{R}$n to Qn, $\overline{Q}$n	3	1.0 1.0	3.4 2.9	4.9 4.5	1.0 1.0	6.2 5.2	ns
t_{OSHL} t_{OSLH}[1]	Output to Output skew An or Bn to $\overline{Y}$n	4		0.5	0.6		0.6	ns

NOTE:
1. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the the same direction, either HIGH–to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

AC SETUP REQUIREMENTS

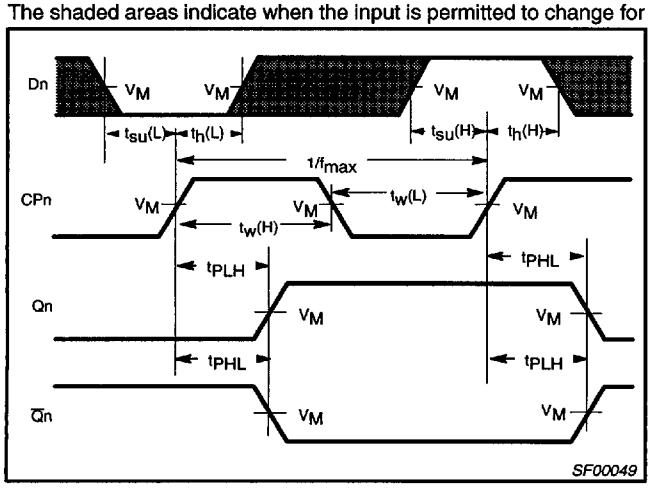
GND = 0V; t_R = t_F = 2.5ns; C_L = 50pF, R_L = 500Ω

SYMBOL	PARAMETER	WAVEFORM	LIMITS			UNIT
			T_{amb} = +25°C V_{CC} = +5.0V		T_{amb} = –40°C to +85°C V_{CC} = +5.0V ±0.5V	
			MIN	TYP	MIN	
t_{su} (H) t_{su} (L)	Setup time, high or low Dn to CPn	1	2.6 2.4	1.4 1.4	2.6 2.4	ns
t_h (H) t_h (L)	Hold time, high or low Dn to CPn	1	0 0	–1.4 –1.4	0 0	ns
t_w (H) t_w (L)	CPn pulse width, high or low	1	1.7 1.7	1.0 1.0	2.1 2.1	ns
t_w (L)	$\overline{S}$Dn, $\overline{R}$Dn pulse width, low	3	2.0	1.3	2.2	ns
t_{rec}	Recovery time $\overline{S}$Dn, $\overline{R}$Dn to CPn	2	2.1	1.4	2.4	ns

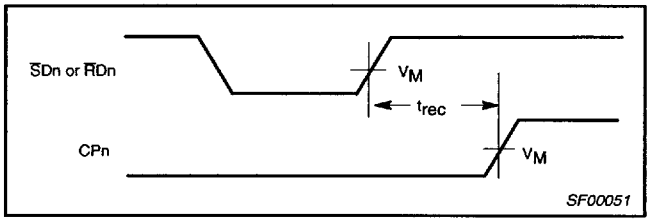
AC WAVEFORMS

V_M = 1.5V, V_{IN} = GND to 3.0V

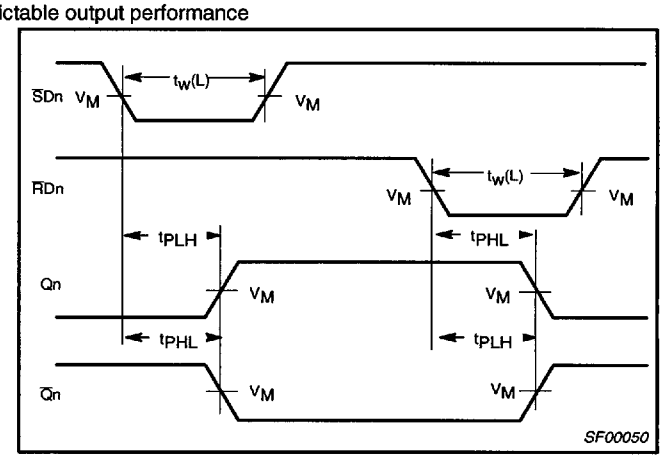
The shaded areas indicate when the input is permitted to change for predictable output performance



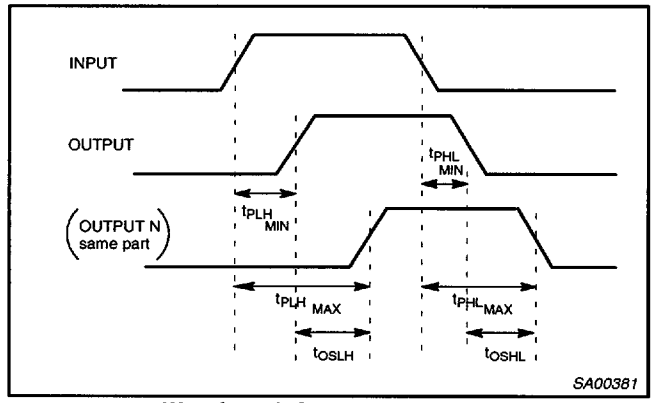
Waveform 1. Propagation delay for data to output, data setup time and hold times, and clock width, and maximum clock frequency



Waveform 2. Recovery time for set or reset to clock

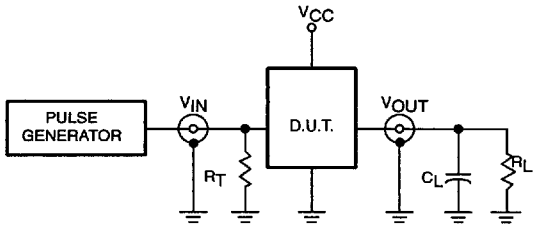


Waveform 3. Propagation delay for set and reset to output, set and reset pulse width

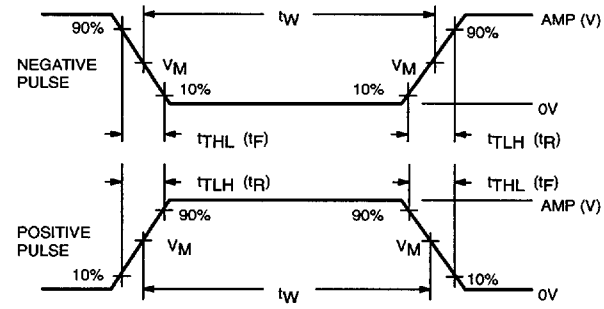


Waveform 4. Common edge skew

TEST CIRCUIT AND WAVEFORMS



Test Circuit for Outputs



V_M = 1.5V

Input Pulse Definition

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value.

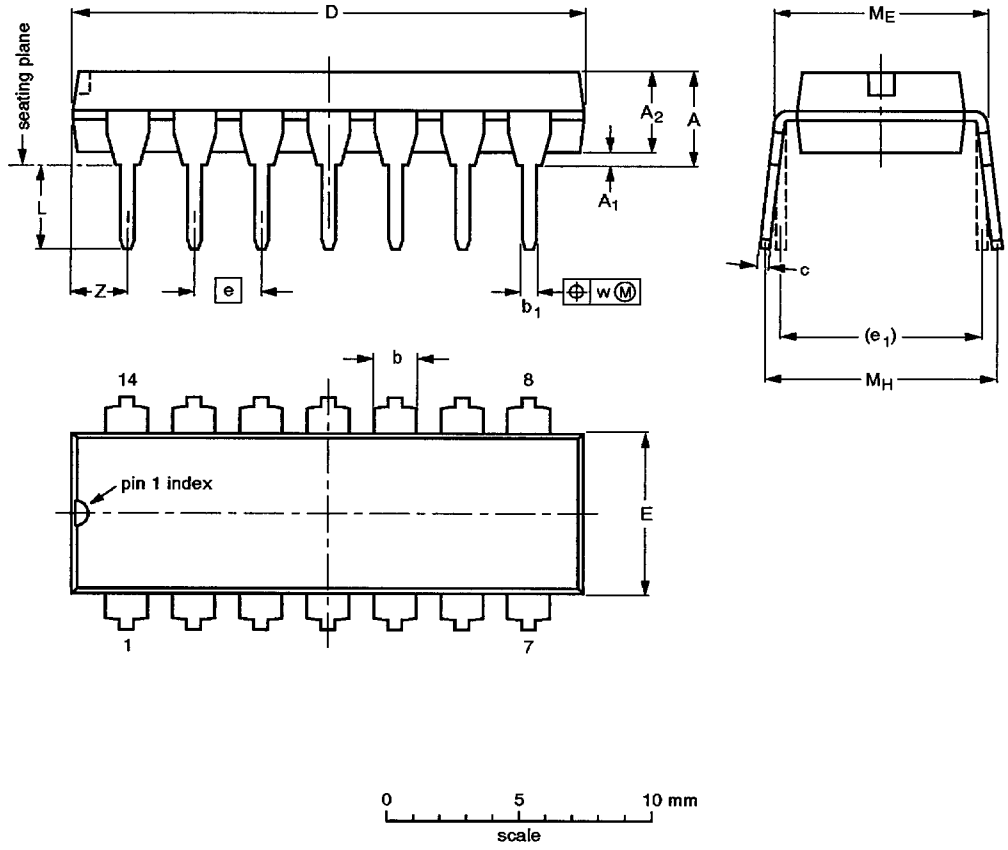
C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	t_W	t_R	t_F
74ABT	3.0V	1MHz	500ns	2.5ns	2.5ns

SH00067

DIP14: plastic dual in-line package; 14 leads (300 mil) SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

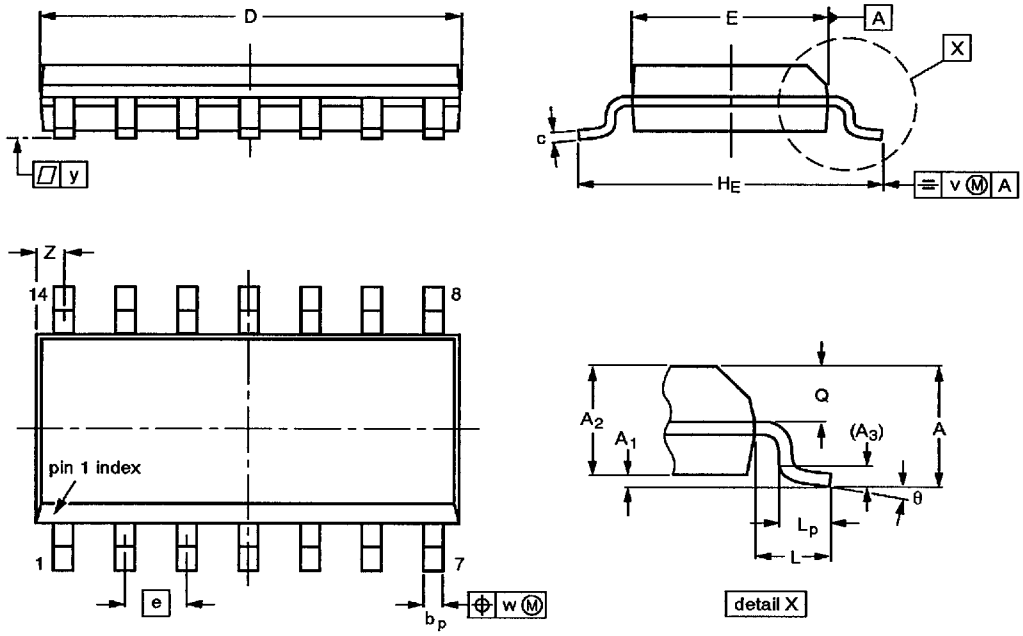
UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

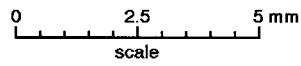
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT27-1	050G04	MO-001AA				~~92-11-17~~ 95-03-11

SO14: plastic small outline package; 14 leads; body width 3.9 mm SOT108-1





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

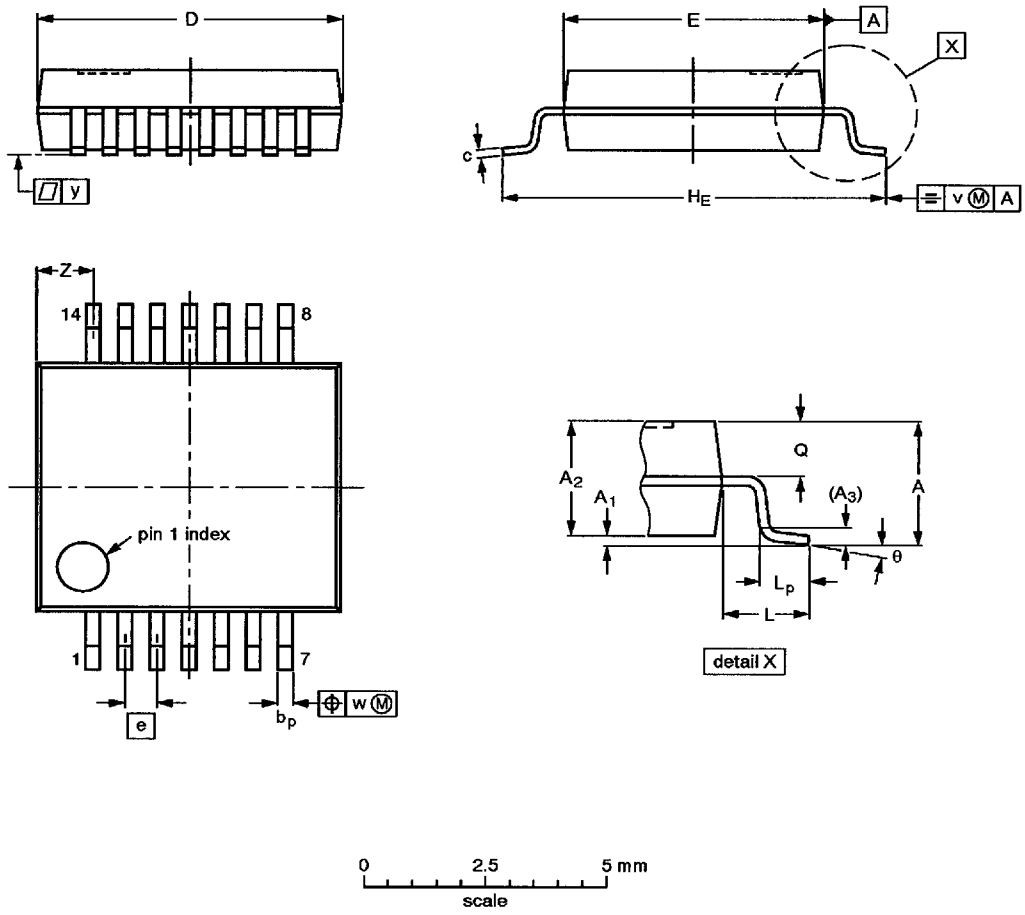
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.0098 0.0039	0.057 0.049	0.01	0.019 0.014	0.0098 0.0075	0.35 0.34	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT108-1	076E06S	MS-012AB				~~91-08-13~~ 95-01-23

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm SOT337-1



DIMENSIONS (mm are the original dimensions)

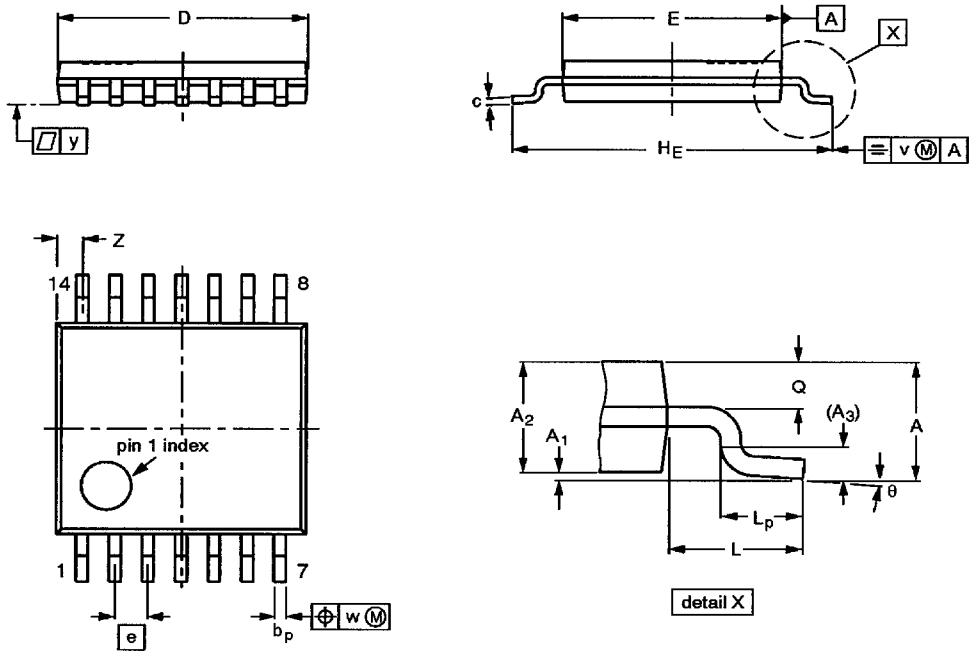
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

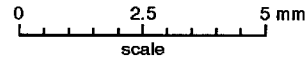
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT337-1		MO-150AB				~~94-01-14~~ 95-02-04

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT402-1		MO-153				~~94-07-12~~ 95-04-04